

Code VIC
Company name Vingroup Joint Stock Company
Date 02/22/2021
Subject Notice of the first public offering of bonds in 2021

Content:

Vingroup Joint Stock Company announces the first public offering of bonds in 2021 as follows:

1. Information on bond offerings:

- Bond type: non-convertible, unsecured bond, no warrants
- Par value: VND100,000/bond
- Total issue volume: 69,750,000 bonds

Of which:

Bond name	Estimated offering volume (bonds)	Issue value at par value (VND)	Total issue value at par value (VND)
The first public offering			
VICB2023001	15,150,000	1,515,000,000,000	1,515,000,000,000
The second public offering			
VICB2124001	10,000,000	1,000,000,000,000	2,860,000,000,000
VICB2124002	18,600,000	1,860,000,000,000	
The third public offering			
VICB2124003	26,000,000	2,600,000,000,000	2,600,000,000,000

2. Information on the first public offering:

- Issuer: Vingroup Joint Stock Company
- Bond name: VICB2023001 Bond
- Bond type: non-convertible, unsecured bond, no warrants
- Par value: VND100,000/bond
- Issue volume: 15,150,000 bonds
- Bond term: 03 years
- Interest payment period: once every 03 months

- Interest rate: combined by floating rates and fixed rates.
- Total capital estimated to be mobilized: VND1,515,000,000,000.
- Purpose of offering: to raise funds for the issuer's subsidiaries
- Offering price: VND100,000/bond
- Subscription time: from January 20, 2021 to February 18, 2021
- Places for subscription and prospectus disclosure:
 - Issue agent: Techcom Securities Joint Stock Company (TCBS)
Address: 2nd Floor, Techcombank Tower, 191 Ba Trieu, Le Dai Hanh, Hai Ba Trung, Ha Noi
 - Place for prospectus announcement: the prospectus and relevant documents are posted on <https://www.tcbs.com.vn/> and <https://vingroup.net/>
- Estimated issue date: February 18, 2021
- Bank for blocking depository money:
 - Account holder: Vingroup Joint Stock Company
 - Account number: 19010302487304
 - Bank: Vietnam Technological and Commercial Joint Stock Bank.